Switch-mode Power Rectifier

Features and Benefits

- Center-Tap Configuration
- Low Forward Voltage
- Low Power Loss / High Efficiency
- High Surge Capacity
- 175°C Operating Junction Temperature
- 15 A Total (7.5 A Per Diode Leg)
- These Devices are Pb-Free and are RoHS Compliant*

Applications

- Power Supply Output Rectification
- Power Management
- Instrumentation

Mechanical Characteristics

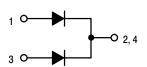
- Case: Epoxy, Molded
- Epoxy Meets UL 94, V-0 @ 0.125 in
- Weight: 1.9 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- ESD Rating: Human Body Model = 3B Machine Model = C

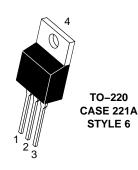


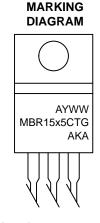
ON Semiconductor®

www.onsemi.com

SCHOTTKY BARRIER RECTIFIERS 15 AMPERES 35 and 45 VOLTS







A = Assembly Location

Y = Year WW = Work Week x = 3 or 4

G = Pb–Free Package AKA = Diode Polarity

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

^{*}For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage MBR1535CT MBR1545CT	V _{RRM} V _{RWM} V _R	35 45	V
Average Rectified Forward Current (T _C = 163°C) Per Diode Per Device	I _{F(AV)}	7.5 15	A
Peak Repetitive Forward Current (Square Wave, 20 kHz, T _C = 161°C) Per Diode	I _{FRM}	15	А
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	IFSM	150	А
Peak Repetitive Reverse Surge Current (2.0 μs, 1.0 kHz)	I _{RRM}	1.0	Α
Storage Temperature Range	T _{stg}	-65 to +175	°C
Operating Junction Temperature (Note 1)	TJ	-65 to +175	°C
Voltage Rate of Change (Rated V _R)	dv/dt	1000	V/μs

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS PER DIODE

Characteristic	Symcbol	Value	Unit
Maximum Thermal Resistance, Junction-to-Case (Min. Pad)	$R_{ heta JC}$	3.0	°C/W
Maximum Thermal Resistance, Junction-to-Ambient (Min. Pad)	$R_{ heta JA}$	60	°C/W

ELECTRICAL CHARACTERISTICS PER DIODE

Characteristic	Symbol	Min	Тур	Max	Unit
Maximum Instantaneous Forward Voltage (Note 2) ($i_F = 7.5 \text{ Amps}$, $T_J = 125^{\circ}\text{C}$) ($i_F = 15 \text{ Amps}$, $T_J = 125^{\circ}\text{C}$) ($i_F = 15 \text{ Amps}$, $T_J = 25^{\circ}\text{C}$)	V _F	- - -	0.47 0.63 0.66	0.57 0.72 0.84	V
Maximum Instantaneous Reverse Current (Note 2) (Rated DC Voltage, $T_J = 125^{\circ}C$) (Rated DC Voltage, $T_J = 25^{\circ}C$)	i _R	- -	10 0.025	15 0.1	mA

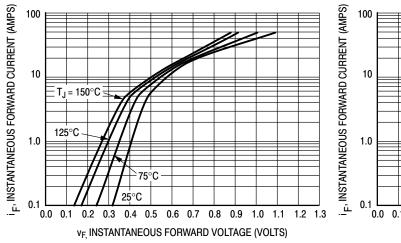
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2.0%

ORDERING INFORMATION

Device	Package	Shipping
MBR1535CTG	TO-220 (Pb-Free)	50 Units / Rail
MBR1545CTG	TO-220 (Pb-Free)	50 Units / Rail

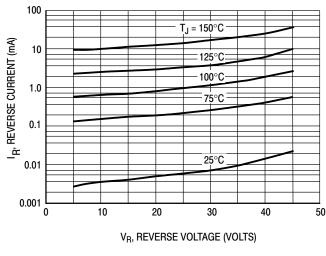
^{1.} The heat generated must be less than the thermal conductivity from Junction–to–Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.



1.0 T_J = 150°C T

Figure 1. Typical Forward Voltage

Figure 2. Maximum Forward Voltage



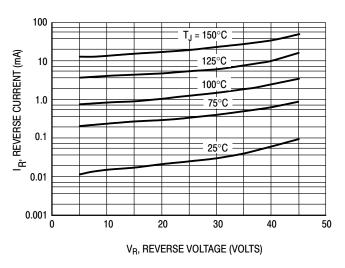
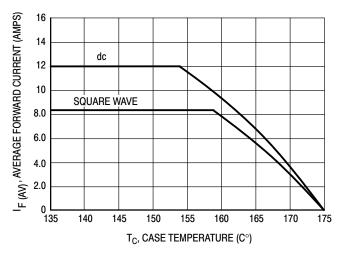


Figure 3. Typical Reverse Current

Figure 4. Maximum Reverse Current



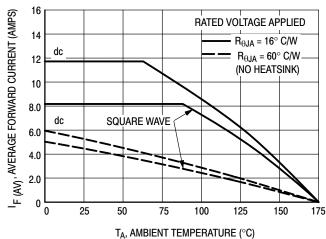
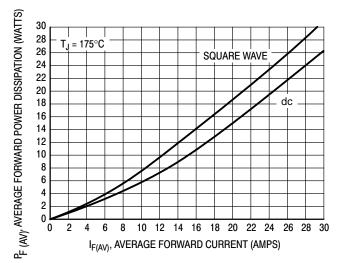


Figure 5. Current Derating, Case Per Leg

Figure 6. Current Derating, Ambient Per Leg





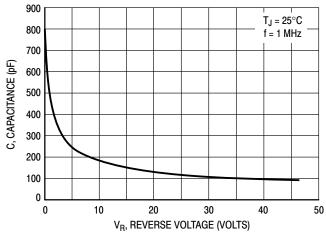
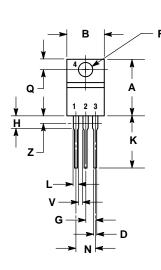
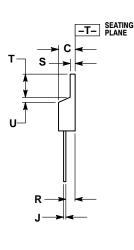


Figure 8. Typical Capacitance

PACKAGE DIMENSIONS

TO-220 CASE 221A-09 **ISSUE AH**





- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.415	9.66	10.53
С	0.160	0.190	4.07	4.83
D	0.025	0.038	0.64	0.96
F	0.142	0.161	3.61	4.09
G	0.095	0.105	2.42	2.66
Н	0.110	0.161	2.80	4.10
J	0.014	0.024	0.36	0.61
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
٧	0.045		1.15	
Z		0.080		2.04

STYLE 6:

PIN 1. ANODE

- CATHODE
- 3. ANODE
- CATHODE

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